

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC030P03NS3 G	**Issued**	22. January 2018
MA#	MA001809742		
Package	PG-TDSON-8-39	**Weight***	114.85 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.418	4.72	4.72	47171	47171
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		127	
	non noble metal	iron	7439-89-6	0.049	0.04		424	
	non noble metal	copper	7440-50-8	48.649	42.37	42.42	423587	424138
wire	non noble metal	copper	7440-50-8	0.023	0.02	0.02	198	198
encapsulation	organic material	carbon black	1333-86-4	0.076	0.07		660	
	plastics	epoxy resin	-	5.986	5.21		52121	
	inorganic material	silicondioxide	60676-86-0	31.825	27.71	32.99	277100	329881
leadfinish	non noble metal	tin	7440-31-5	1.520	1.32	1.32	13235	13235
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1380	1380
solder	non noble metal	tin	7440-31-5	0.081	0.07		705	
	noble metal	silver	7440-22-4	0.101	0.09		882	
	non noble metal	lead	7439-92-1	3.868	3.37	3.53	33678	35265
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		44	
	non noble metal	iron	7439-89-6	0.017	0.01		147	
	noble metal	silver	7440-22-4	0.150	0.13		1306	
	non noble metal	copper	7440-50-8	16.910	14.72	14.86	147235	148732
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com